

# MA22D23

## Silicon epitaxial planar type

For high frequency rectification

### ■ Features

- $I_{F(AV)} = 1$  A rectification is possible.
- High  $I_{FSM}$  ( $I_{FSM} = 30$  A)
- Small reverse current  $I_R$ .

### ■ Package

- Code  
Mini2-F1
- Pin Name  
1: Anode  
2: Cathode

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	25	V
Repetitive peak reverse voltage	$V_{RRM}$	25	V
Forward current (Average) *1	$I_{F(AV)}$	1.0	A
Non-repetitive peak forward surge current *2	$I_{FSM}$	30	A
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +125	$^\circ\text{C}$

### ■ Marking Symbol: 3W

Note) \*1: Mounted on a alumina PC board

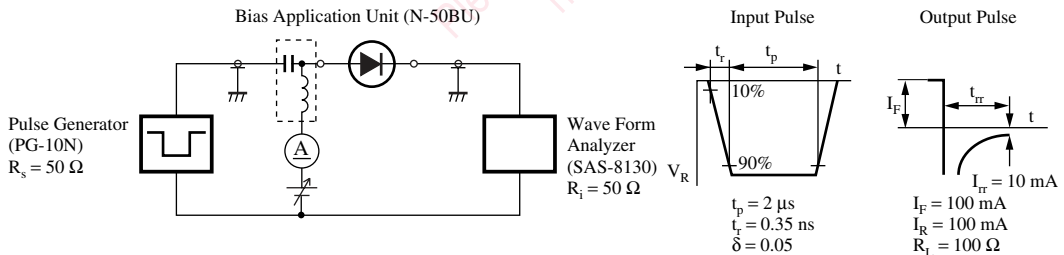
\*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

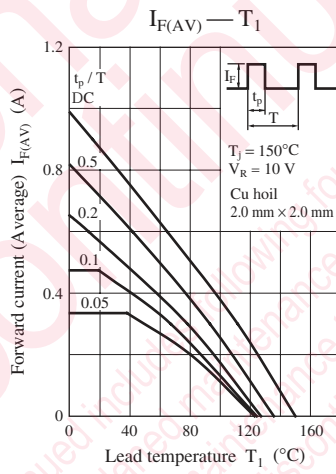
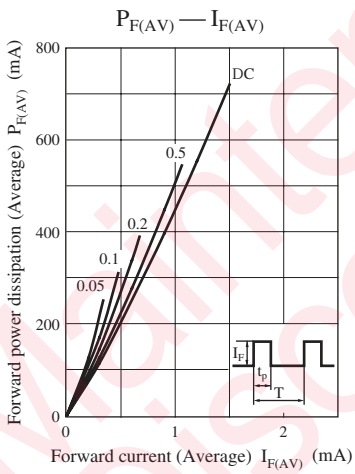
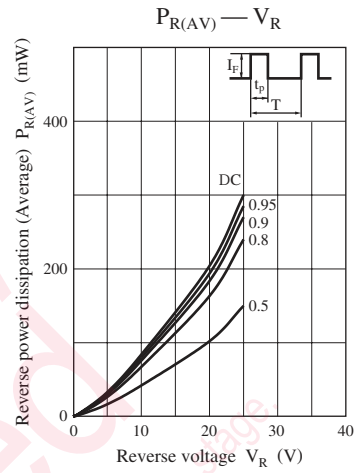
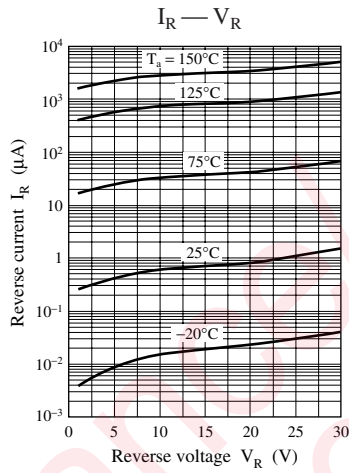
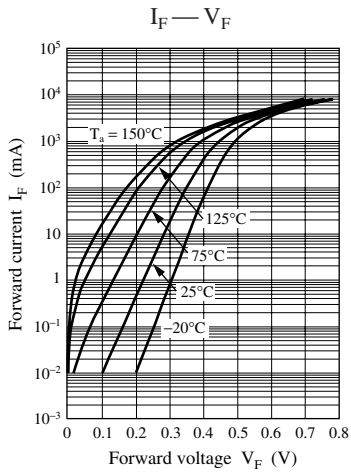
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse current	$I_{R1}$	$V_R = 15$ V		1.5	20	$\mu\text{A}$
	$I_{R2}$	$V_R = 20$ V		2.5	40	
Forward voltage	$V_{F1}$	$I_F = 0.5$ A		0.41	0.46	V
	$V_{F2}$	$I_F = 1.0$ A		0.44	0.53	
Terminal capacitance	$C_t$	$V_R = 10$ V, $f = 1$ MHz		45		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

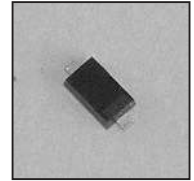
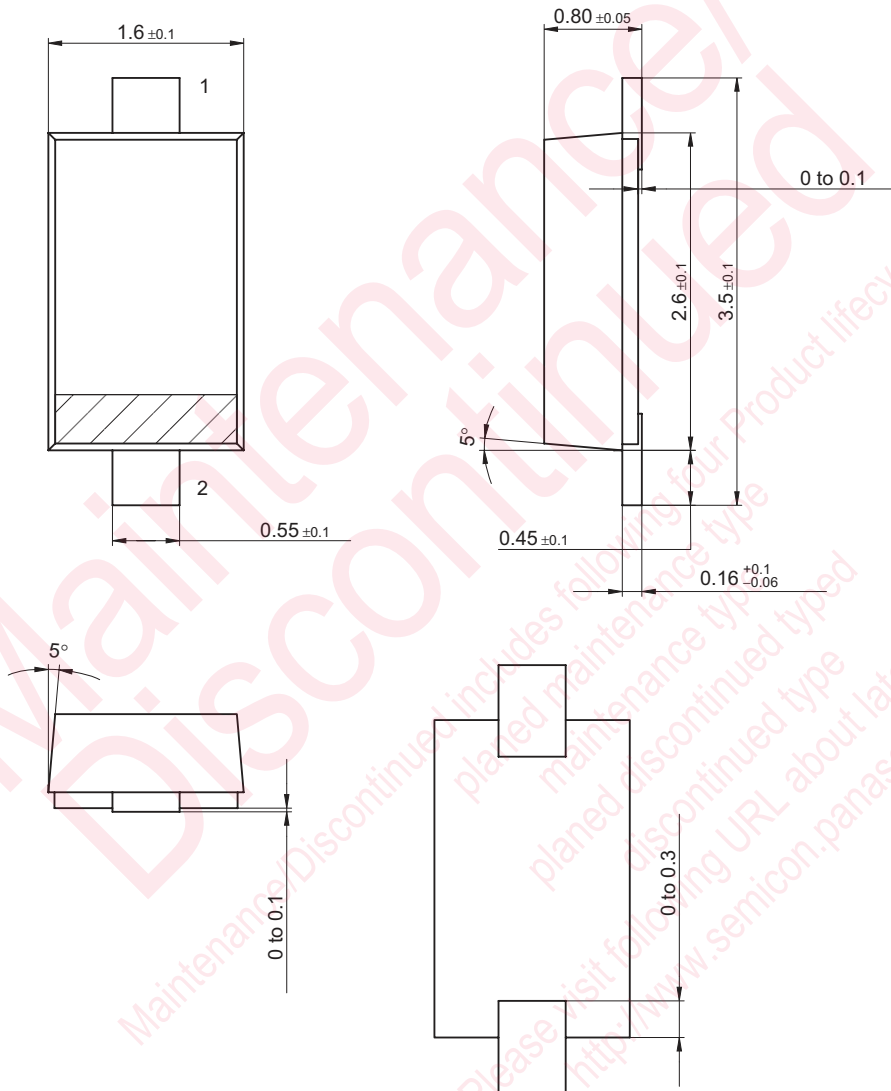
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.





Mini2-F1

Unit: mm



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